



US00D709040S

(12) **United States Design Patent**  
**Chen et al.**

(10) **Patent No.:** **US D709,040 S**

(45) **Date of Patent:** **\*\* \*Jul. 15, 2014**

(54) **LIGHT EMITTING DIODE PACKAGE**

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(\*) Notice: This patent is subject to a terminal disclaimer.

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/438,300**

(22) Filed: **Nov. 28, 2012**

(30) **Foreign Application Priority Data**

Nov. 12, 2012 (TW) ..... 101306654

(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/180**

(58) **Field of Classification Search**  
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;  
H01L 27/156; H01L 31/02; H01L 33/00;  
H01L 33/04; H01L 33/08; H01L 33/10;  
H01L 33/20; H01L 33/38; H01L 33/42;  
H01L 33/4862; H01L 33/483; H01L 33/486  
USPC ..... D13/180; D26/1; 257/79, 80, 81, 88,  
257/89, 95, 98, 99, 100, E33.058; 313/483,  
313/498, 500; 362/555, 800

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D505,397 S *	5/2005	Asakawa	.....	D13/180
D517,025 S *	3/2006	Asakawa	.....	D13/180
D568,261 S *	5/2008	Lee et al.	.....	D13/180
D576,573 S *	9/2008	Kobayakawa	.....	D13/180
D592,617 S *	5/2009	Bando	.....	D13/180
D593,967 S *	6/2009	Fushimi	.....	D13/180
D619,110 S *	7/2010	Lin et al.	.....	D13/180
D624,885 S *	10/2010	Lin et al.	.....	D13/180
D662,902 S *	7/2012	Shieh et al.	.....	D13/180
D674,361 S *	1/2013	Lin et al.	.....	D13/180
D693,780 S *	11/2013	Chen et al.	.....	D13/180
D695,239 S *	12/2013	Ko et al.	.....	D13/180
D698,047 S *	1/2014	Sasaoka et al.	.....	D26/1
D698,742 S *	2/2014	Niikura et al.	.....	D13/180
2012/0104426 A1 *	5/2012	Chan et al.	.....	257/89

\* cited by examiner

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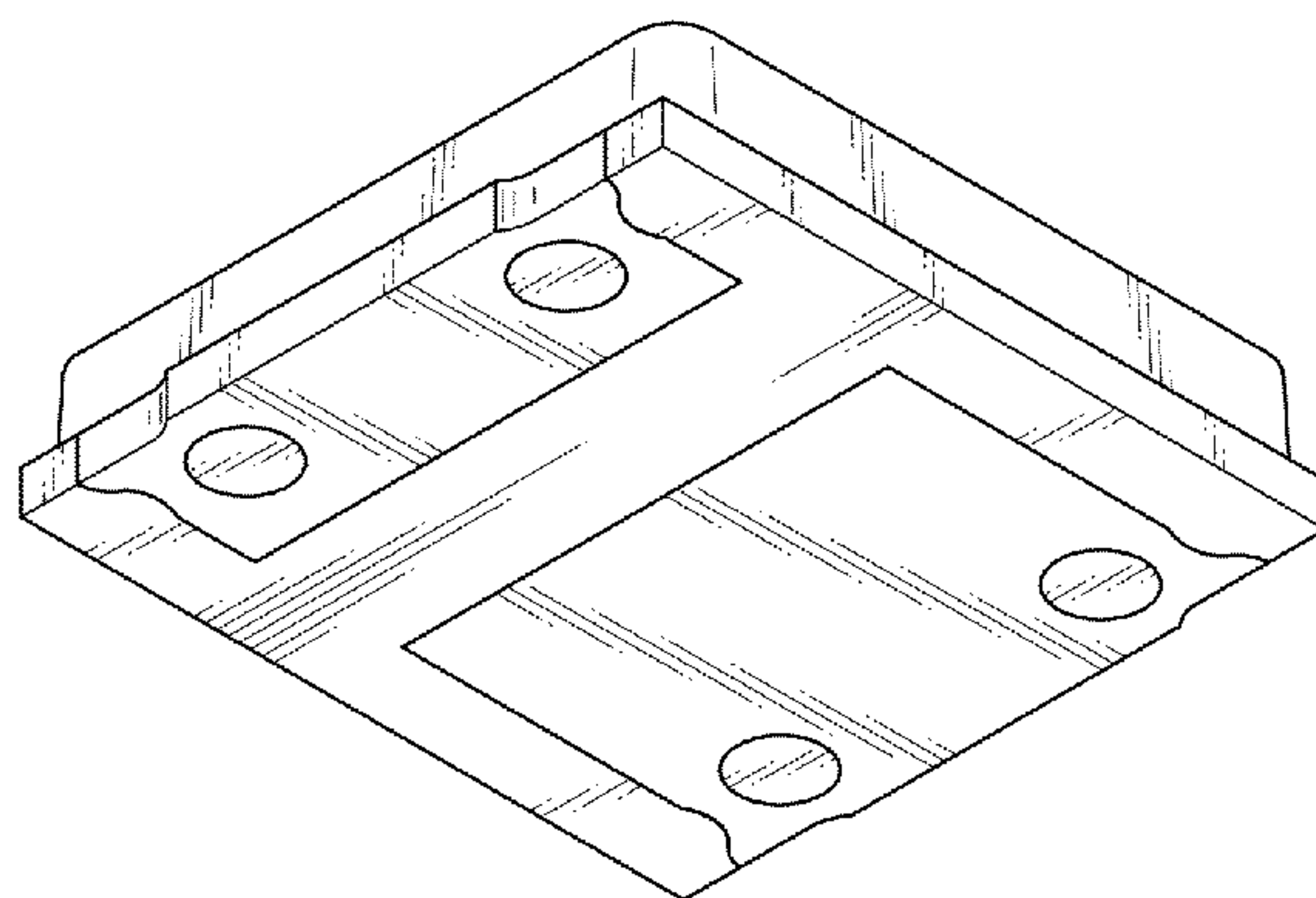
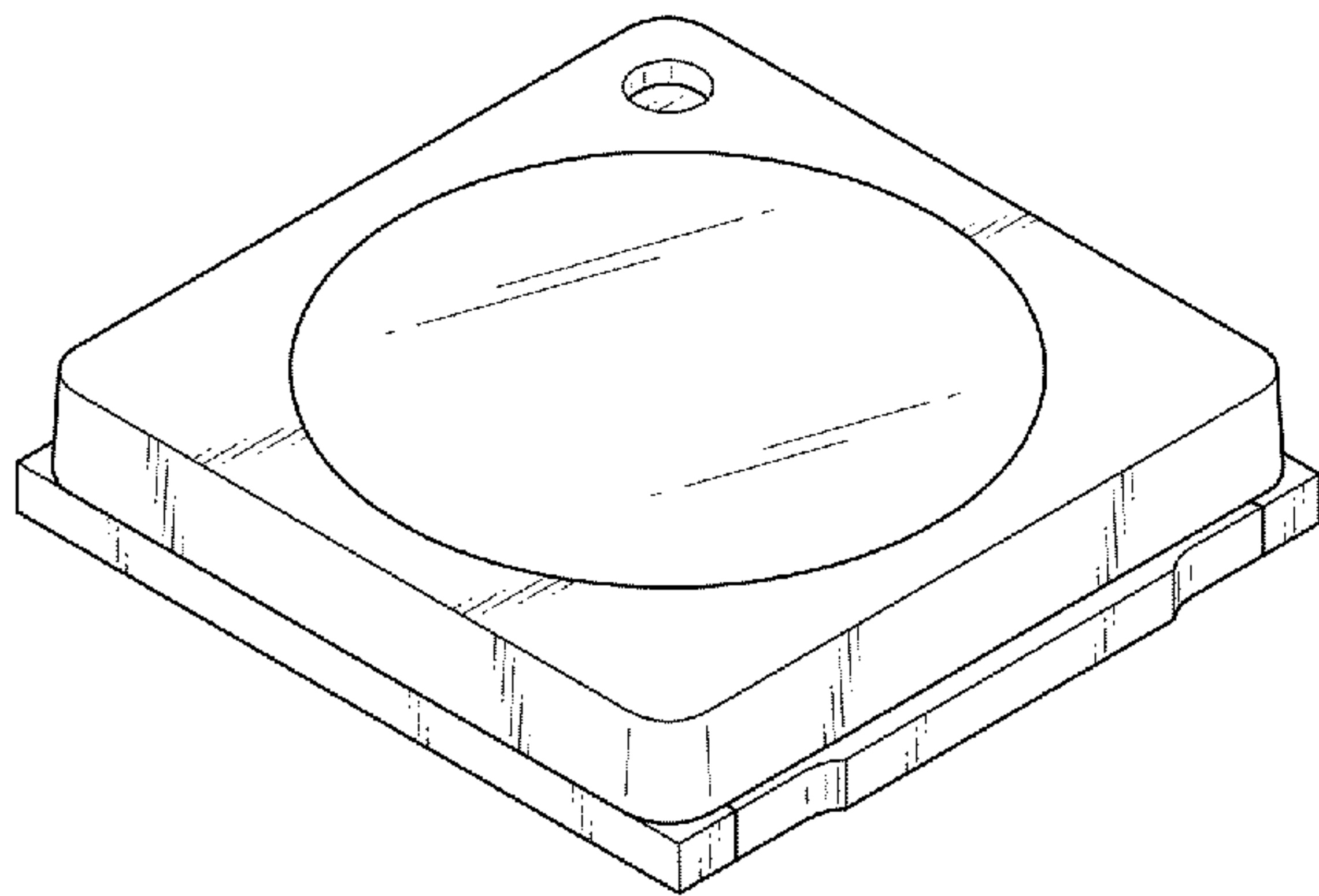
(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown and described.

**DESCRIPTION**

FIG. 1 is a front perspective view of a light emitting diode package showing the new design;  
FIG. 2 is another perspective view thereof;  
FIG. 3 is a front elevational view thereof;  
FIG. 4 is a rear elevational view thereof;  
FIG. 5 is a left side elevational view thereof;  
FIG. 6 is a right side elevational view thereof;  
FIG. 7 is a top plan view thereof; and,  
FIG. 8 is a bottom plan view thereof.

**1 Claim, 8 Drawing Sheets**



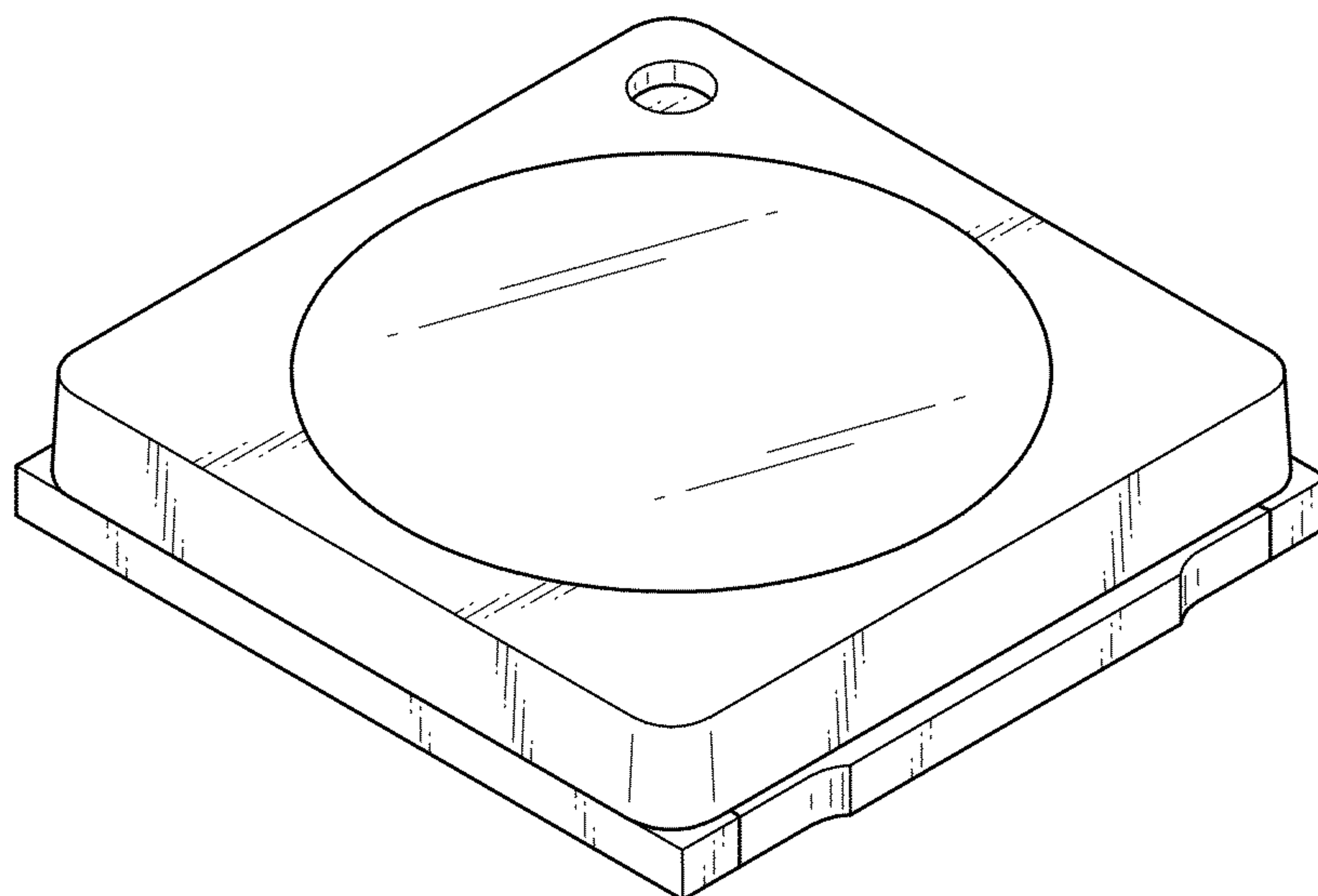


FIG. 1

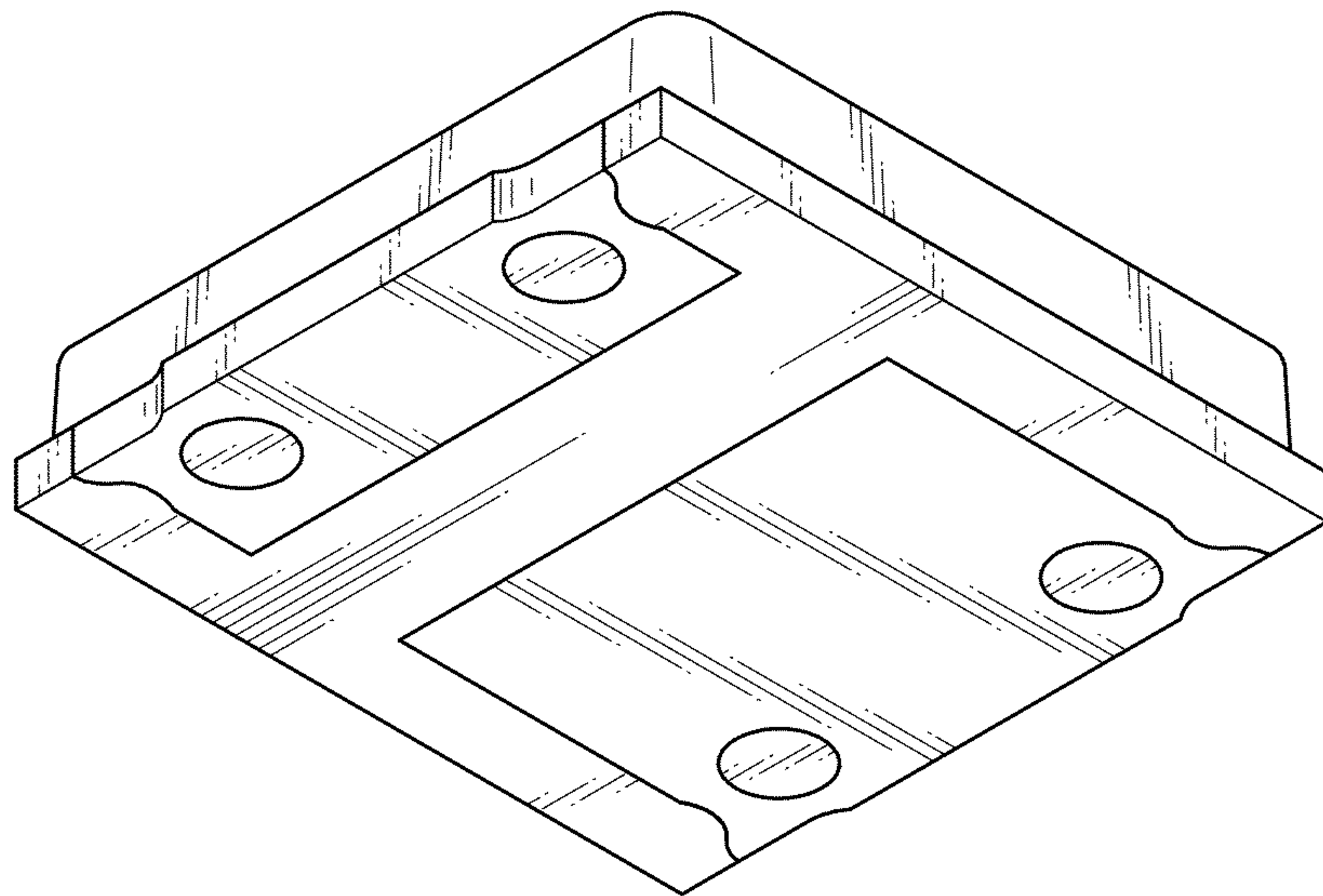


FIG.2

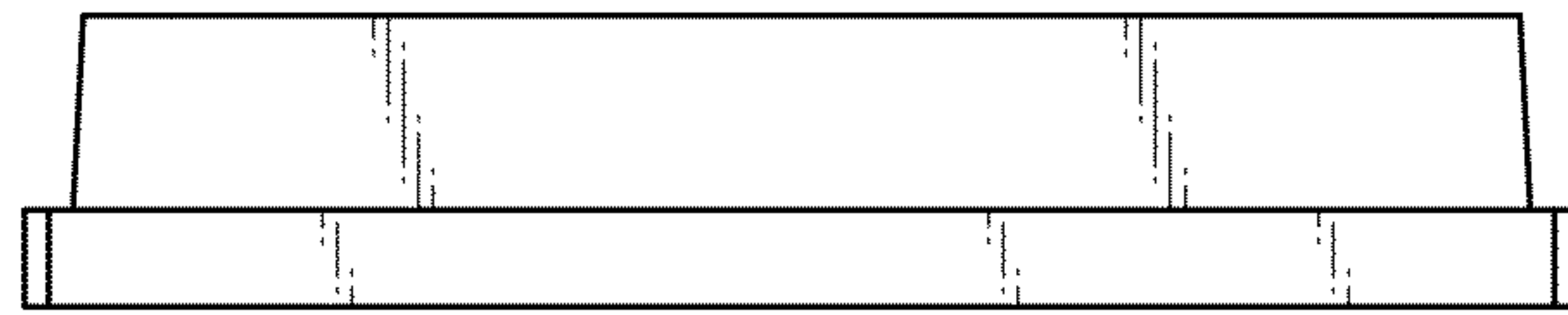


FIG.3

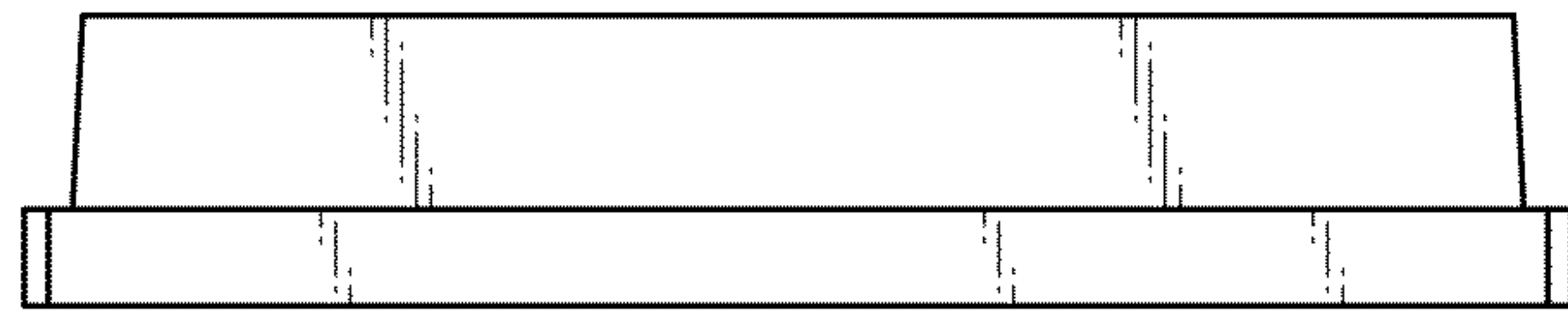


FIG.4

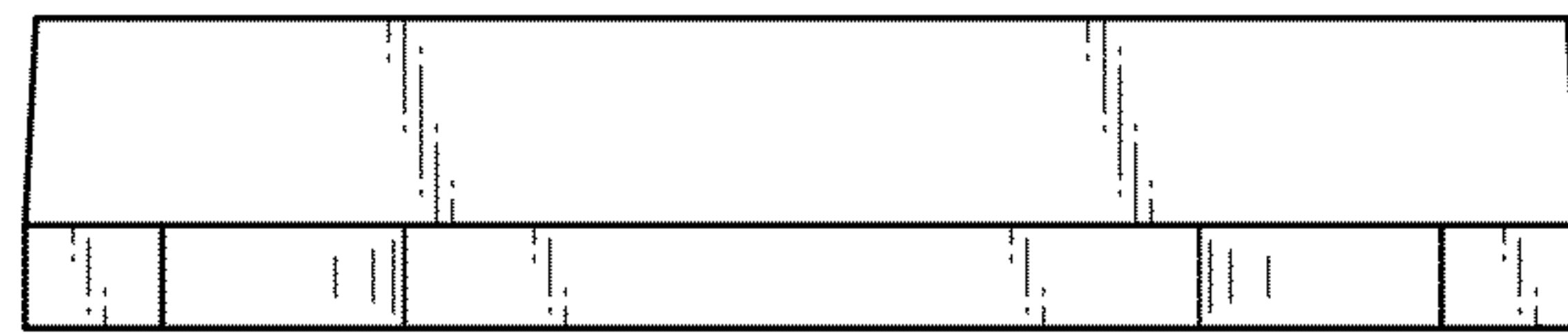


FIG.5

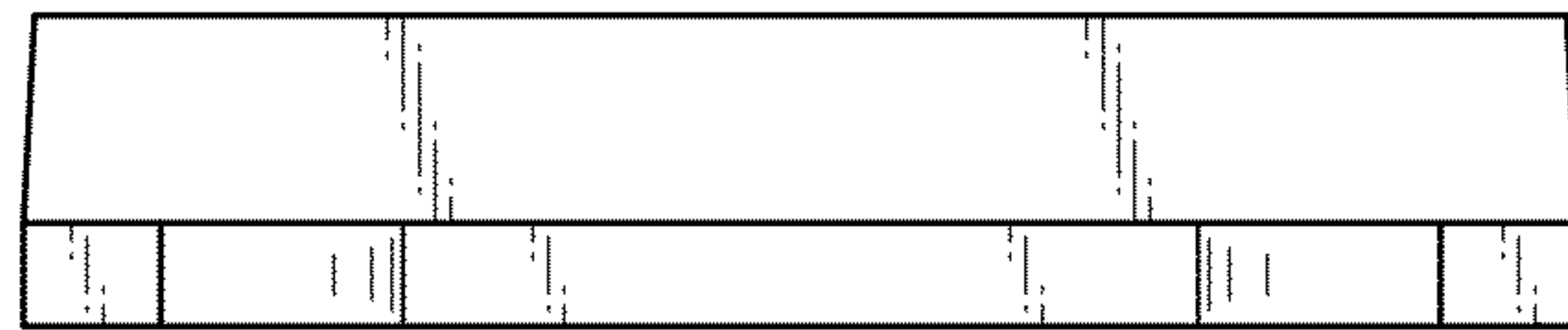


FIG.6

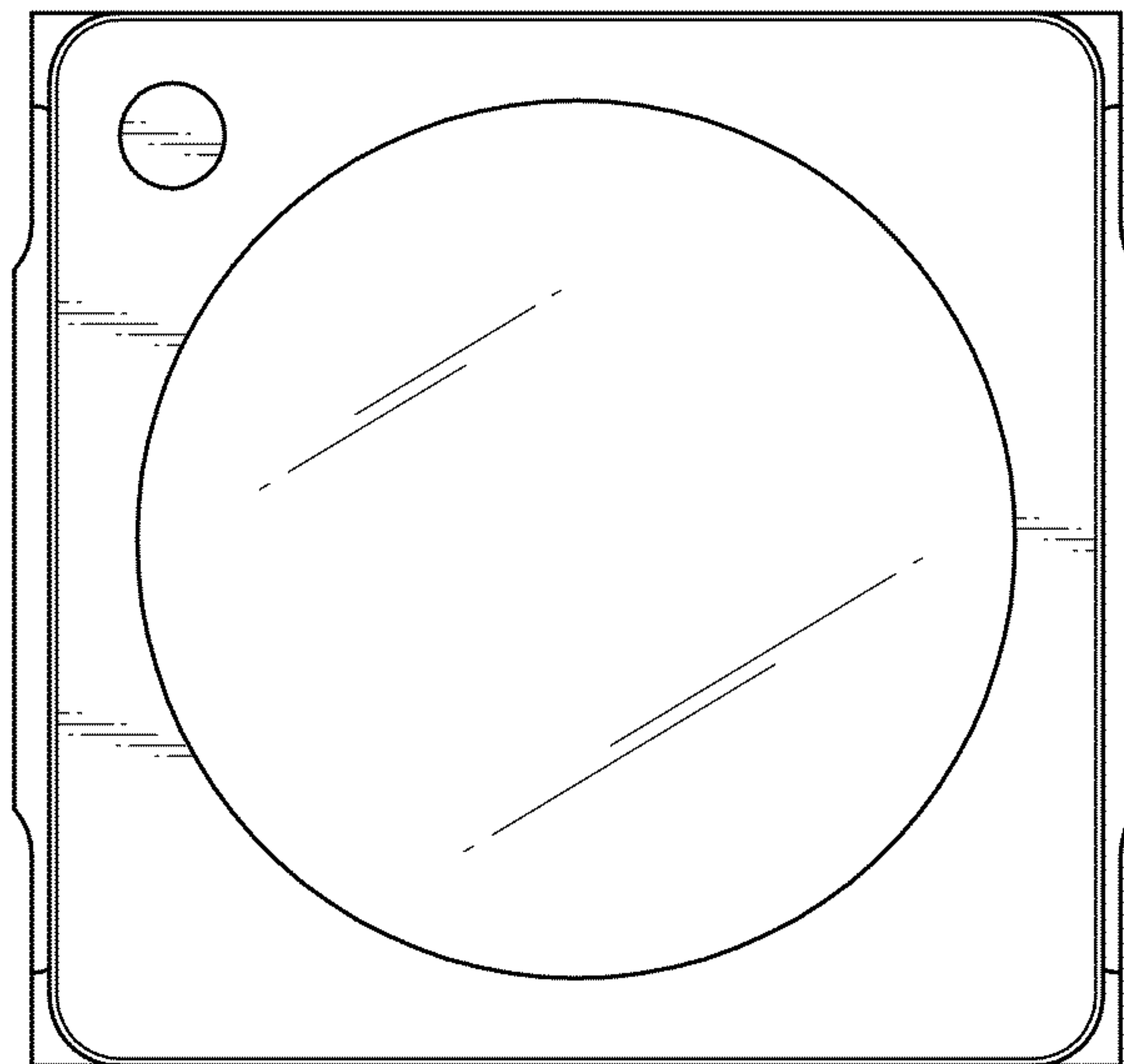


FIG. 7



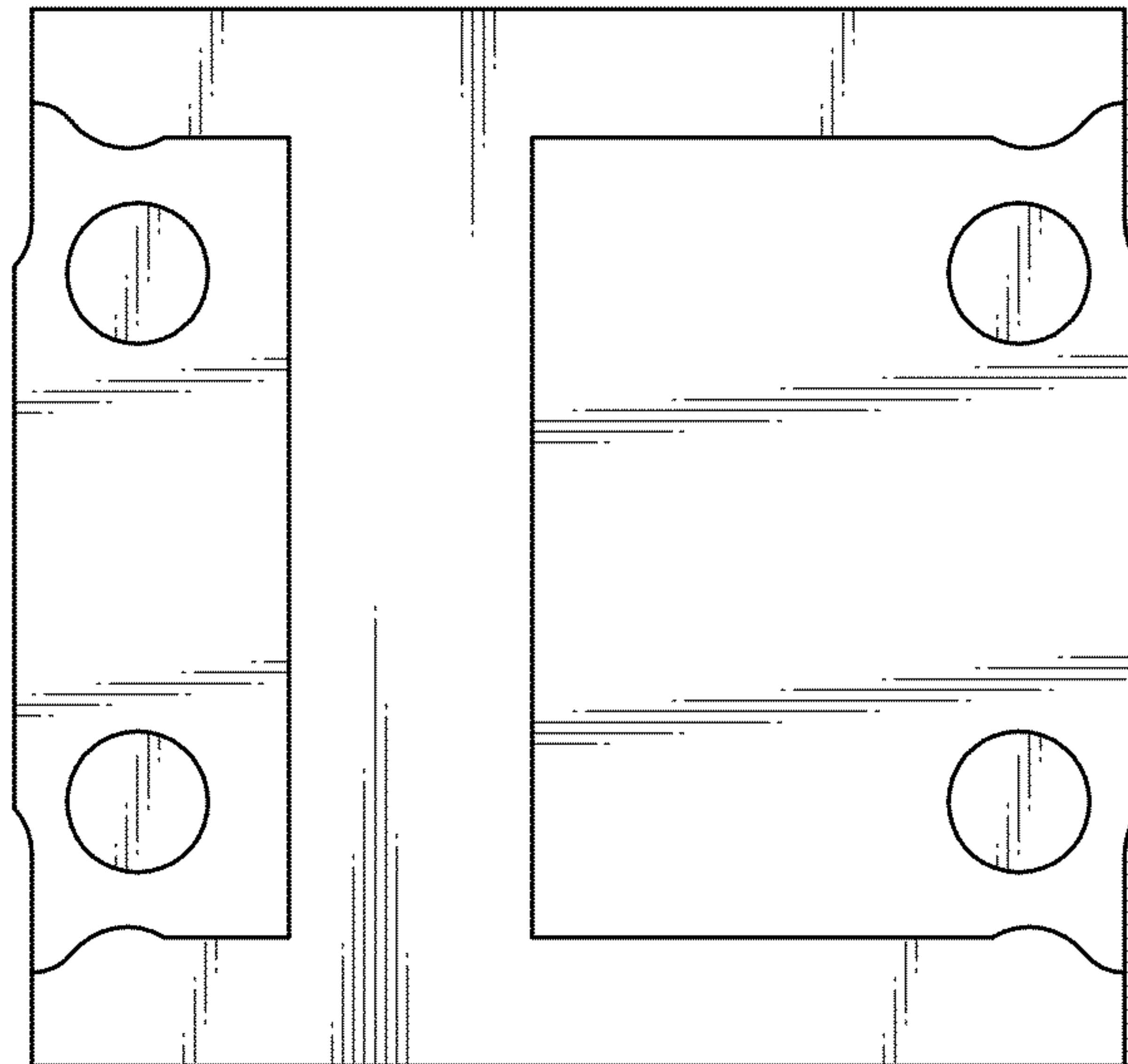


FIG.8